

IFX24401

Low Dropout Voltage Regulator

IFX24401TEV50
IFX24401ELV50

Data Sheet

Rev. 1.02, 2009-12-10

Standard Power



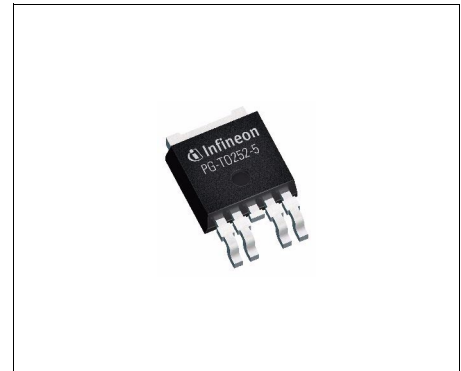
1 Overview

Features

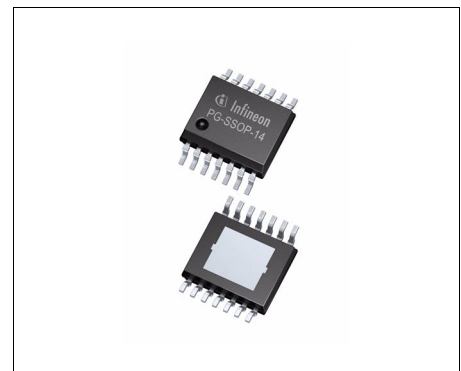
- Output voltage 5 V \pm 2%
- Ultra low current consumption: 20 μ A (typ.)
- 300 mA current capability
- Enable input
- Very low-drop voltage
- Short circuit protection
- Overtemperature protection
- Low Dropout Voltage, 250mV (typ.)
- High Input Voltage 45 V
- Temperature Range $-40\text{ }^{\circ}\text{C} \leq T_j \leq 125\text{ }^{\circ}\text{C}$
- Green Product (RoHS compliant)

Applications

- Battery powered devices (e.g. Handheld GPS)
- Portable Radios
- HDTV Televisions
- Game Consoles
- Network Routers



PG-TO252-5



PG-SSOP-14

For automotive and transportation applications, please refer to the Infineon TLE and TLF voltage regulator series.

Functional Description

The IFX24401 is a monolithic integrated low-drop voltage regulator for load currents up to 300 mA. The output voltage is regulated to $V_{Q,nom} = 5.0\text{ V}$ with an accuracy of \pm 2%. A sophisticated design allows stable operation with low ESR ceramic output capacitors down to 470 nF. The device is designed for the harsh environments. Therefore it is protected against overload, short circuit and overtemperature conditions. Due to its ultra low stand-by current consumption of 20 μ A (typ.) the IFX24401 is ideal for use in battery powered applications. The regulator can be shut down via an Enable input which further reduces the current consumption to 5 μ A (typ.). An integrated output sink current circuitry keeps the voltage at the Output pin Q below 5.5 V even when reverse currents are applied. Thus connected devices are protected from overvoltage damage.

| Type | Package | Marking |
|---------------|------------|----------|
| IFX24401TEV50 | PG-TO252-5 | 2440150 |
| IFX24401ELV50 | PG-SSOP-14 | 24401V50 |

2 Block Diagram

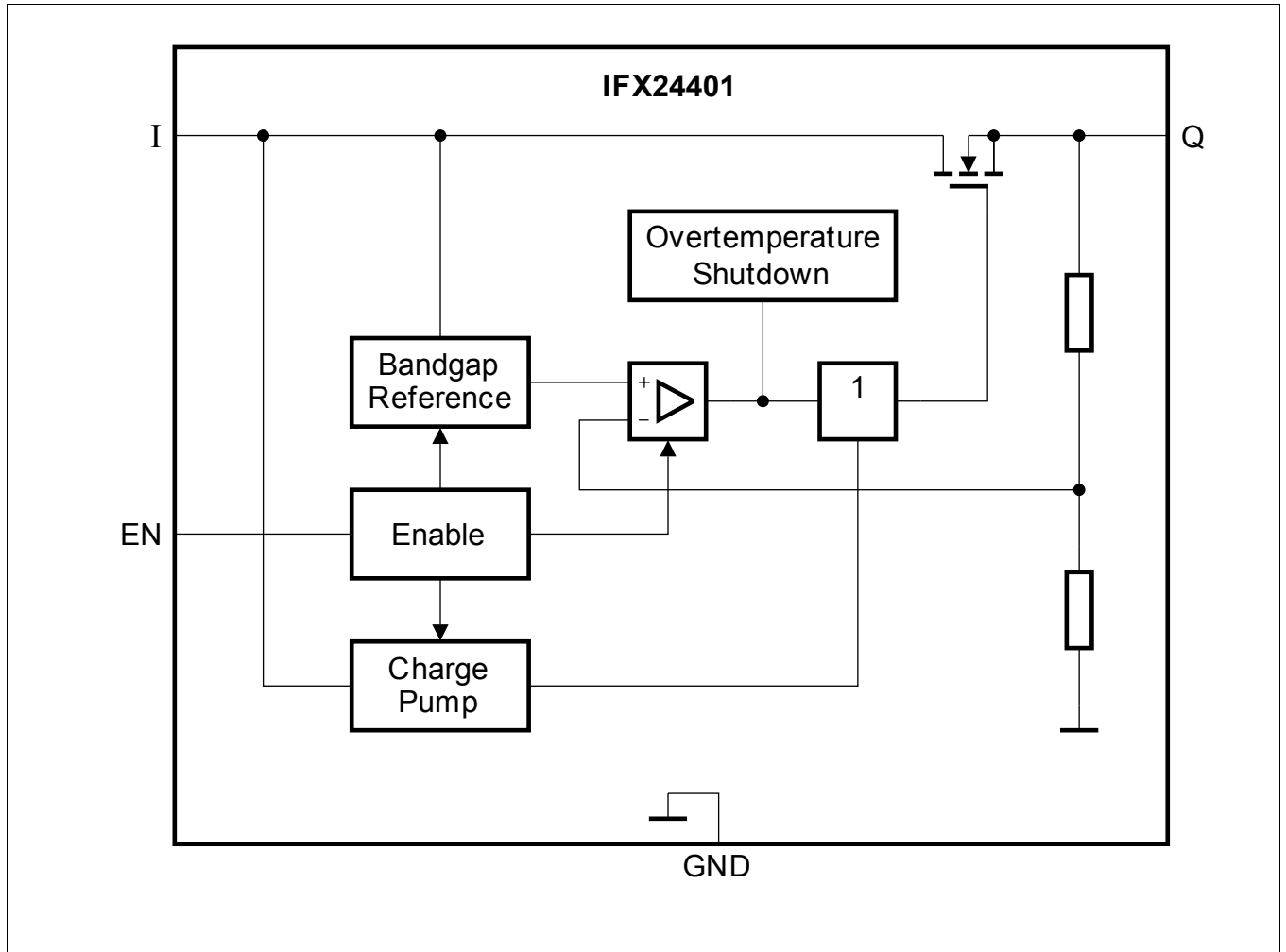


Figure 1 Block Diagram

3 Pin Configuration

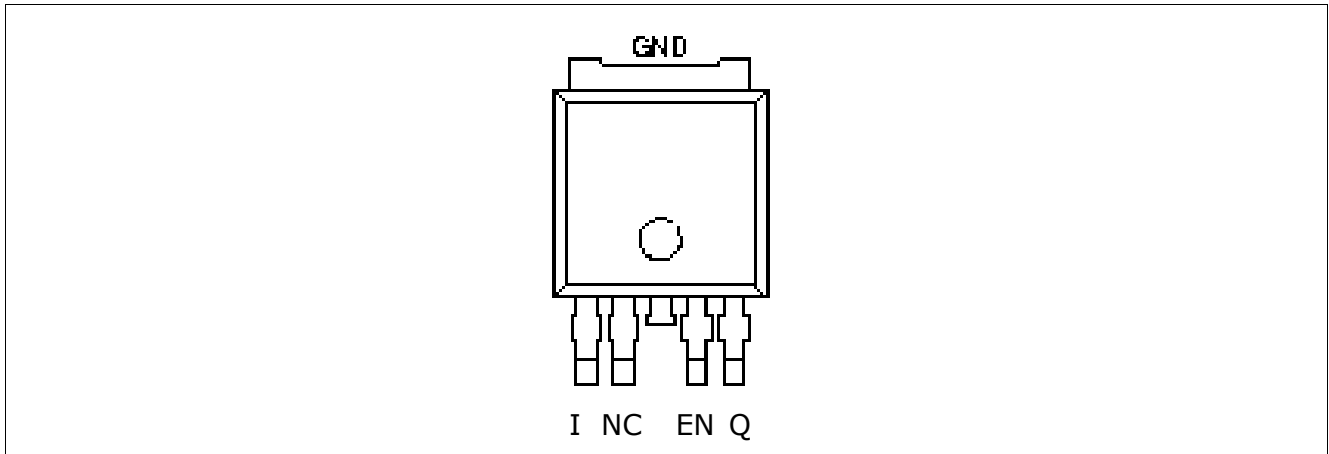


Figure 2 Pin Configuration PG-TO252-5 (top view)

3.1 Pin Definitions and Functions (PG-TO252-5)

| Pin | Symbol | Function |
|-----------|--------|---|
| 1 | I | Input Connect ceramic capacitor between I and GND |
| 2 | N.C. | No Connect May be open or connected to GND |
| 3 | GND | Ground Internally connected to heat slug |
| 4 | EN | Enable Input Low signal level disables the regulator. Pull-down resistor is integrated. |
| 5 | Q | Output Place capacitor between Q pin and GND. Capacitor placement should be close to pin. Refer to capacitance and ESR requirements in "Functional Range" on Page 6 |
| Heat Slug | -- | Heat Slug Connect to board GND and heatsink |

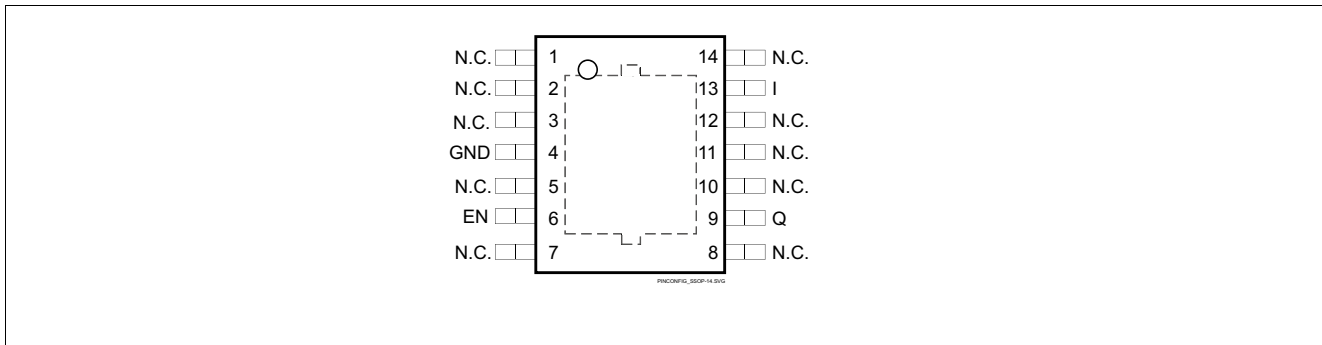


Figure 3 Pin Configuration PG-SSOP-14 (top view)

3.2 Pin Definitions and Functions (PG-SSOP-14)

| Pin | Symbol | Function |
|---------------|--------|--|
| 1,2,3,5,7 | N.C. | No Connect May be open or connected to GND |
| 4 | GND | Ground |
| 6 | EN | Enable Input Low signal level disables the regulator. Pull-down resistor is integrated. |
| 8,10,11,12,14 | N.C. | No Connect May be open or connected to GND |
| 9 | Q | Output Place capacitor between Q pin and GND. Capacitor placement should be close to pin. Refer to capacitance and ESR requirements in “Functional Range” on Page 6 |
| 13 | I | Input Connect ceramic capacitor between I and GND |
| Pad | | Exposed Pad Connect to board GND and heatsink |

4 General Product Characteristics

4.1 Absolute Maximum Ratings

Absolute Maximum Ratings¹⁾

$T_j = -40\text{ °C}$ to 150 °C ; all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

| Parameter | Symbol | Limit Values | | Unit | Test Condition |
|----------------------|-----------|--------------|------|------|---|
| | | Min. | Max. | | |
| Input I | | | | | |
| Voltage | V_I | -0.3 | 45 | V | – |
| Current | I_I | -1 | – | mA | – |
| Enable EN | | | | | |
| Voltage | V_{EN} | -0.3 | 45 | V | Observe current limit $I_{EN,max}^{2)}$ |
| Current | I_{EN} | -1 | 1 | mA | – |
| Output Q | | | | | |
| Voltage | V_Q | -0.3 | 5.5 | V | – |
| Voltage | V_Q | -0.3 | 6.2 | V | $t < 10\text{ s}^{3)}$ |
| Current | I_Q | -1 | – | mA | – |
| Temperature | | | | | |
| Junction temperature | T_j | -40 | 150 | °C | – |
| Storage temperature | T_{stg} | -50 | 150 | °C | – |

1) Not subject to production test, specified by design.

2) External resistor required to keep current below absolute maximum rating when voltages $\geq 5.5\text{ V}$ are applied.

3) Exposure to these absolute maximum ratings for extended periods ($t > 10\text{ s}$) may affect device reliability.

Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

4.2 Functional Range

| Parameter | Symbol | Limit Values | | Unit | Remarks |
|----------------------|---------------|--------------|------|----------|---------------------|
| | | Min. | Max. | | |
| Input voltage | V_I | 5.5 | 42 | V | – |
| Junction temperature | T_j | -40 | 125 | °C | – |
| Output Capacitor | C_Q | 470 | – | nF | ¹⁾ |
| | ESR (C_Q) | – | 10 | Ω | $f = 10\text{ kHz}$ |

1) The minimum output capacitance requirement is applicable for a worst case capacitor tolerance of 30%

Note: In the operating range, the functions given in the circuit description are fulfilled.

4.3 Thermal Resistance

| Pos. | Parameter | Symbol | Limit Value | | | Unit | Conditions |
|-------------------------------------|-----------------------------------|------------|-------------|------|------|------|---|
| | | | Min. | Typ. | Max. | | |
| IFX24401TEV50 (PG-TO252-5,) | | | | | | | |
| 4.3.1 | Junction to Case ¹⁾ | R_{thJC} | – | 4 | – | K/W | measured to pin 5 |
| 4.3.2 | Junction to Ambient ¹⁾ | R_{thJA} | – | 115 | – | K/W | Footprint only ²⁾ |
| 4.3.3 | | | – | 57 | – | K/W | 300mm ² heatsink area on PCB ²⁾ |
| 4.3.4 | | | – | 42 | – | K/W | 600mm ² heatsink area on PCB ²⁾ |
| IFX24401ELV50 (PG-SSOP-14) | | | | | | | |
| 4.3.5 | Junction to Case ¹⁾ | R_{thJC} | – | 7 | – | K/W | measured to pin 5 |
| 4.3.6 | Junction to Ambient ¹⁾ | R_{thJA} | – | 120 | – | K/W | Footprint only ²⁾ |
| 4.3.7 | | | – | 59 | – | K/W | 300mm ² heatsink area on PCB ²⁾ |
| 4.3.8 | | | – | 49 | – | K/W | 600mm ² heatsink area on PCB ²⁾ |

1) not subject to production test, specified by design

2) EIA/JESD 52_2, FR4, 80 × 80 × 1.5 mm; 35μ Cu, 5μ Sn

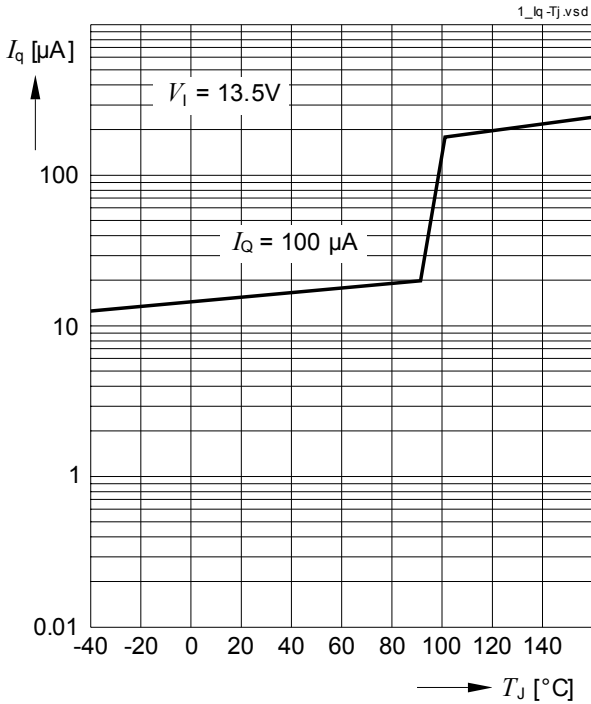
Table 1 Electrical Characteristics
 $V_I = 13.5 \text{ V}; V_{EN} = 5 \text{ V}; -40 \text{ }^\circ\text{C} < T_j < 125 \text{ }^\circ\text{C}$ (unless otherwise specified)

| Parameter | Symbol | Limit Values | | | Unit | Measuring Condition |
|---|--------------------|--------------|------|------|---------------|--|
| | | Min. | Typ. | Max. | | |
| Output Q | | | | | | |
| Output voltage | V_Q | 4.9 | 5.0 | 5.1 | V | $0.1 \text{ mA} < I_Q < 300 \text{ mA};$ $6 \text{ V} < V_I < 16 \text{ V}$ |
| Output voltage | V_Q | 4.9 | 5.0 | 5.1 | V | $0.1 \text{ mA} < I_Q < 100 \text{ mA};$ $6 \text{ V} < V_I < 40 \text{ V}$ |
| Output current limit | $I_{Q,LIM}$ | 320 | – | – | mA | 1) |
| Output current limit | $I_{Q,LIM}$ | – | – | 800 | mA | $V_Q = 0 \text{ V}$ |
| Current consumption; $I_q = I_I - I_Q$ | I_q | – | 20 | 30 | μA | $I_Q = 0.1 \text{ mA};$ $T_j = 25 \text{ }^\circ\text{C}$ |
| Current consumption; $I_q = I_I - I_Q$ | I_q | – | – | 40 | μA | $I_Q = 0.1 \text{ mA};$ $T_j \leq 80 \text{ }^\circ\text{C}$ |
| Quiescent current; Disabled | I_q | – | 5 | 9 | μA | $V_{EN} = 0 \text{ V};$ $T_j < 80 \text{ }^\circ\text{C}$ |
| Drop voltage | V_{dr} | – | 250 | 500 | mV | $I_Q = 200 \text{ mA};$ $V_{dr} = V_I - V_Q$ 1) |
| Load regulation | $\Delta V_{Q, lo}$ | -40 | 15 | 40 | mV | $I_Q = 5 \text{ mA to } 250 \text{ mA}$ |
| Line regulation | $\Delta V_{Q, li}$ | -20 | 5 | 20 | mV | $V_I = 10 \text{ V to } 32 \text{ V};$ $I_Q = 5 \text{ mA}$ |
| Power supply ripple rejection | $PSRR$ | – | 60 | – | dB | $f_r = 100 \text{ Hz};$ $V_r = 0.5 \text{ Vpp}$ |
| Temperature output voltage drift | dV_Q/dT | – | 0.5 | – | mV/K | – |
| Enable Input EN | | | | | | |
| Turn-on Voltage | $V_{EN ON}$ | 3.1 | – | – | V | $V_Q \geq 4.9 \text{ V}$ |
| Turn-off Voltage | $V_{EN OFF}$ | – | – | 0.8 | V | $V_Q \leq 0.3 \text{ V}$ |
| H-input current | $I_{EN ON}$ | – | 3 | 4 | μA | $V_{EN} = 5 \text{ V}$ |
| L-input current | $I_{EN OFF}$ | – | 0.5 | 1 | μA | $V_{EN} = 0 \text{ V};$ $T_j < 80 \text{ }^\circ\text{C}$ |

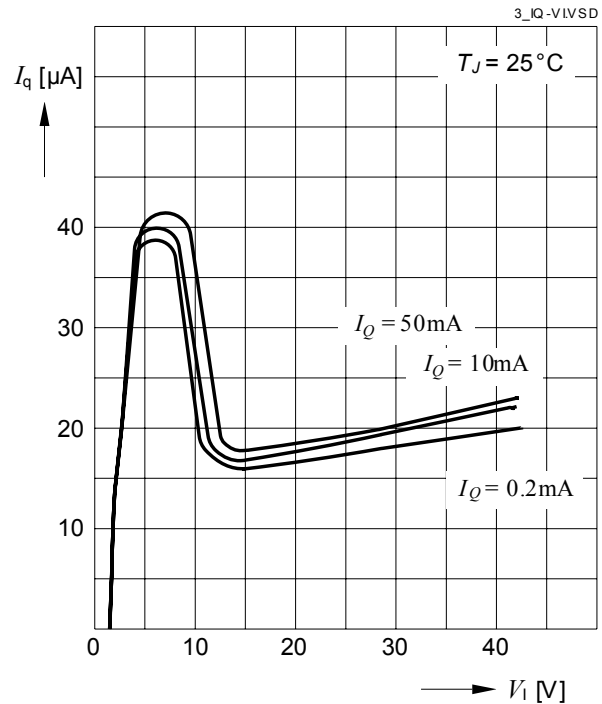
1) Measured when the output voltage V_Q has dropped 100 mV from the nominal value obtained at $V_I = 13.5 \text{ V}$.

5 Typical Performance Characteristics

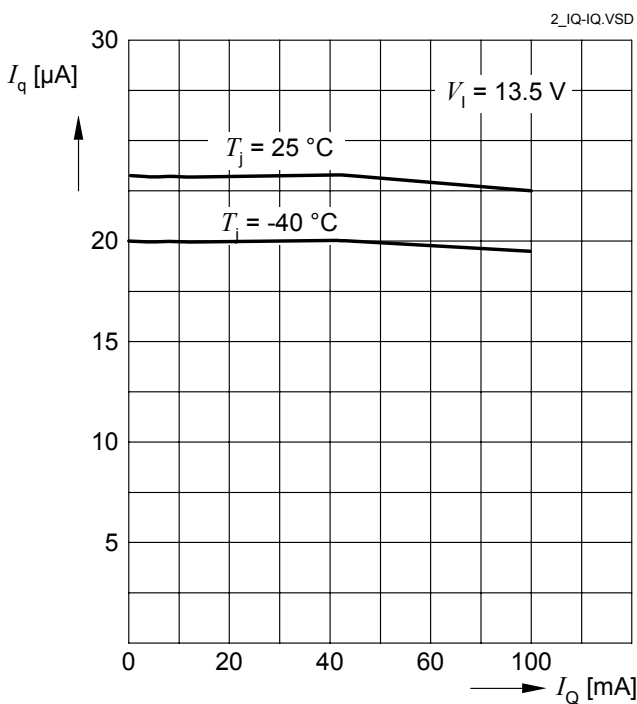
Current Consumption I_q versus Junction Temperature T_j



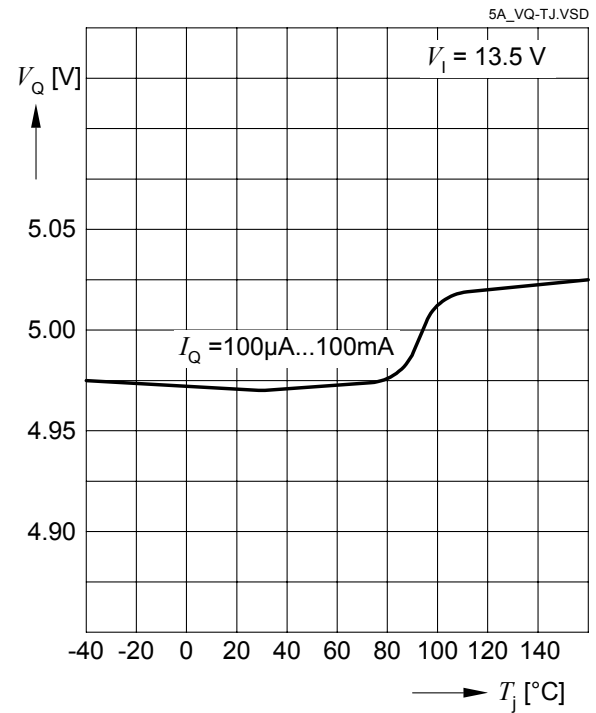
Current Consumption I_q versus Input Voltage V_i



Current Consumption I_q versus Output Current I_Q

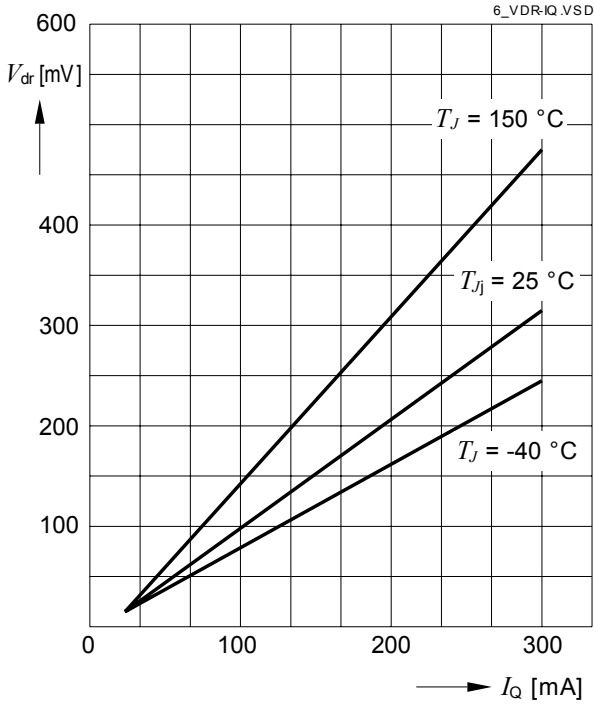


Output Voltage V_Q versus Junction Temperature T_j

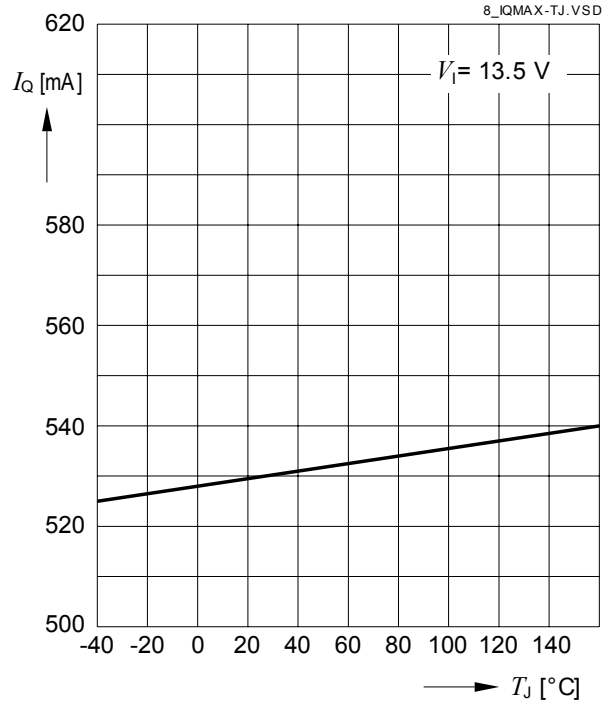


Typical Performance Characteristics

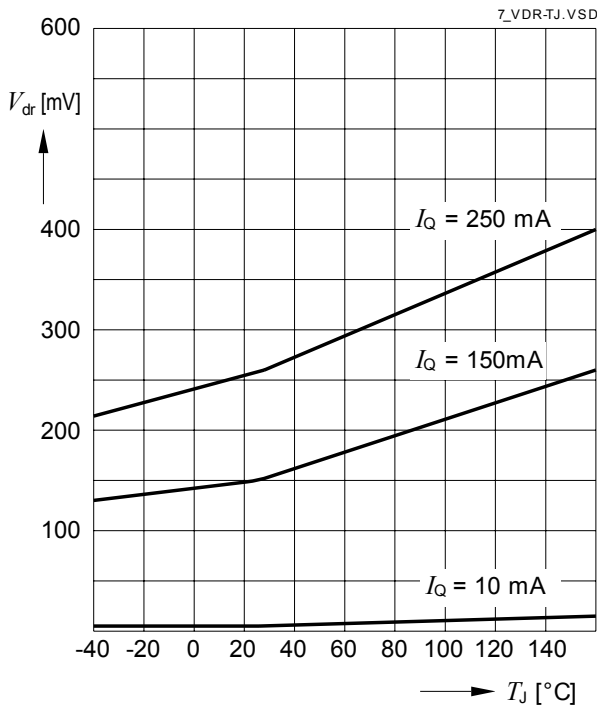
Dropout Voltage V_{dr} versus Output Current I_Q



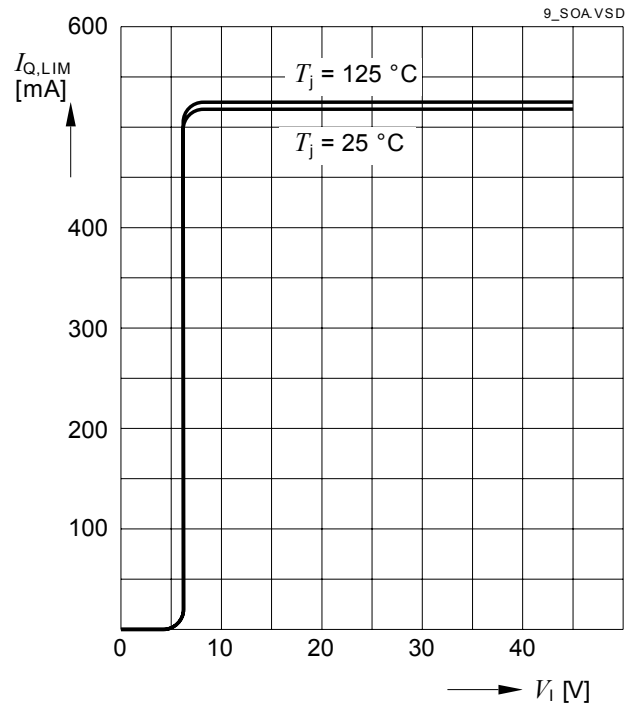
Maximum Output Current I_Q versus Junction Temperature T_j



Dropout Voltage V_{dr} versus Junction Temperature

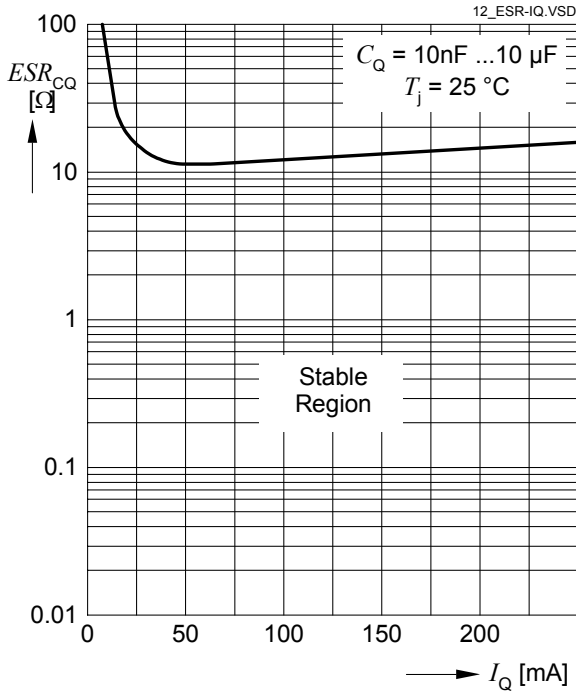


Maximum Output Current I_Q versus Input Voltage V_1

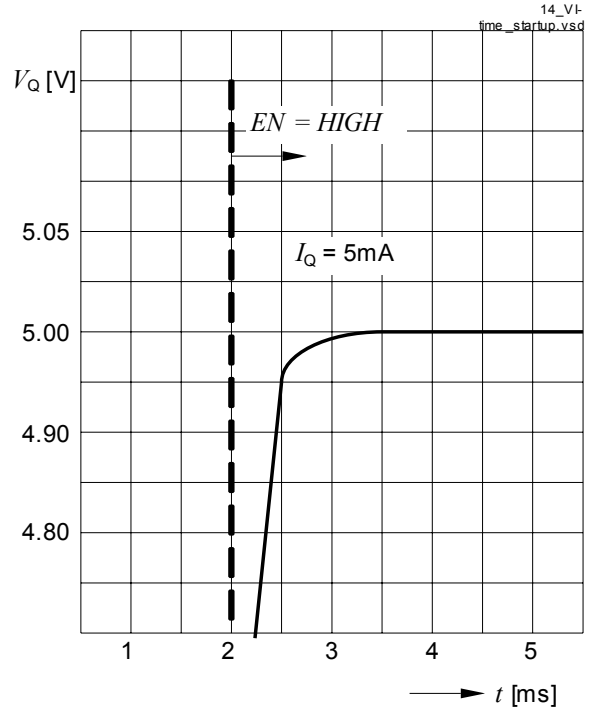


Typical Performance Characteristics

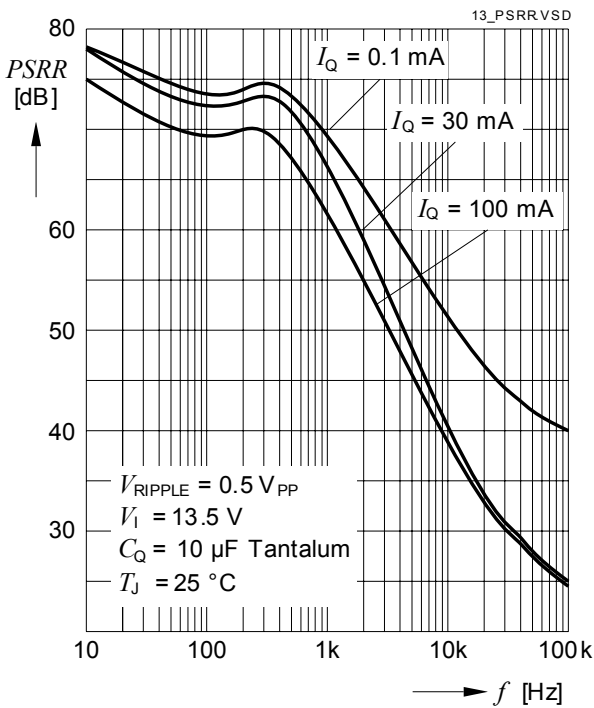
Region of Stability



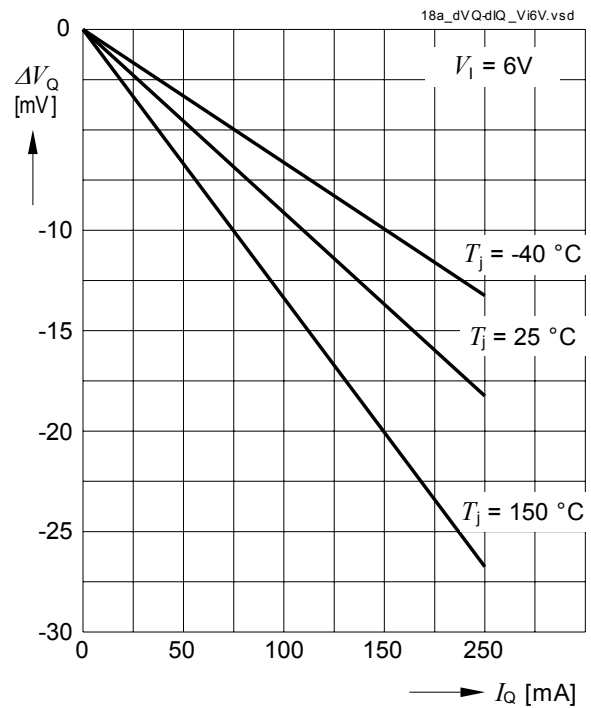
Output Voltage V_Q Start-up behavior



Power Supply Ripple Rejection PSRR versus Frequency f

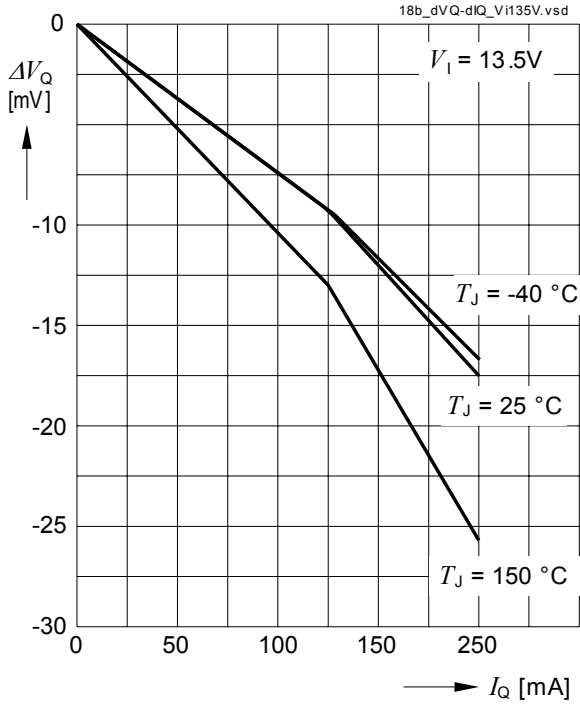


Load Regulation ΔV_Q versus Output Current Change ΔI_Q

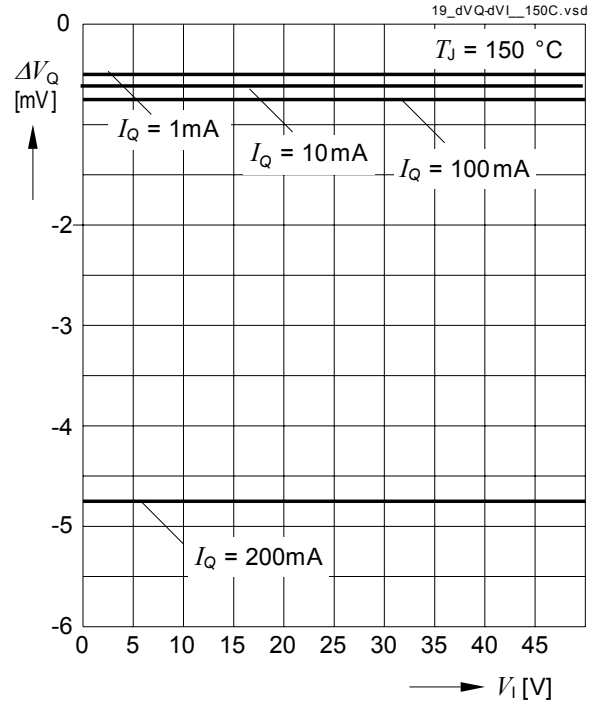


Typical Performance Characteristics

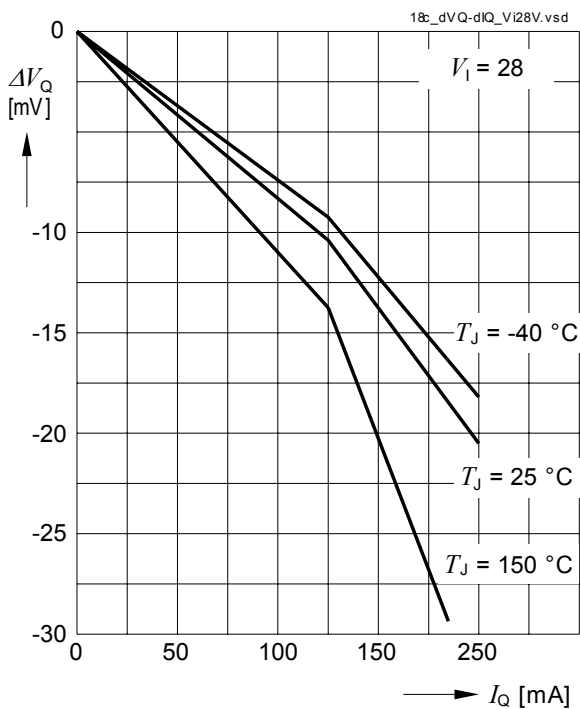
Load Regulation ΔV_Q versus Output Current Change dI_Q



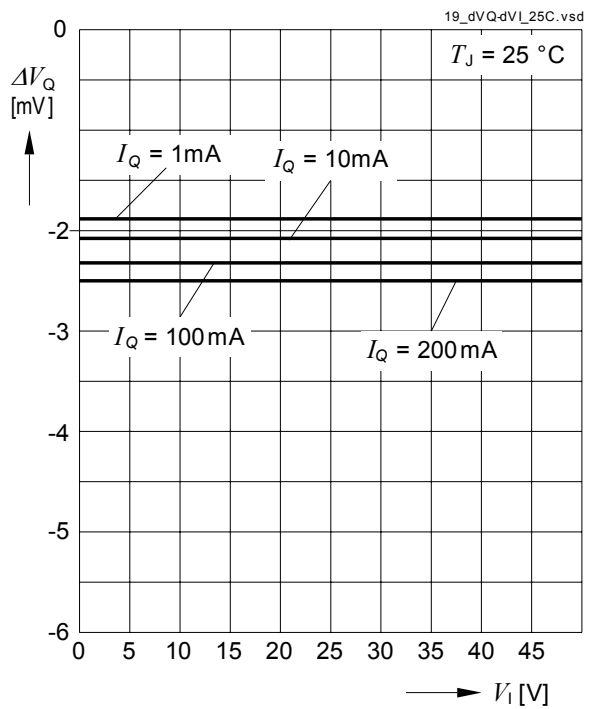
Line Regulation ΔV_Q versus Input Voltage Changed V_1



Load Regulation ΔV_Q versus Output Current Change ΔI_Q

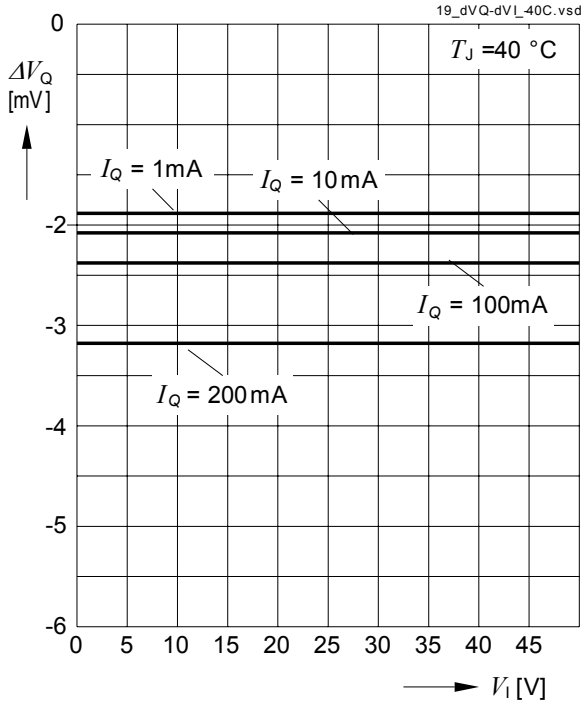


Line Regulation ΔV_Q versus Input Voltage Changed V_1

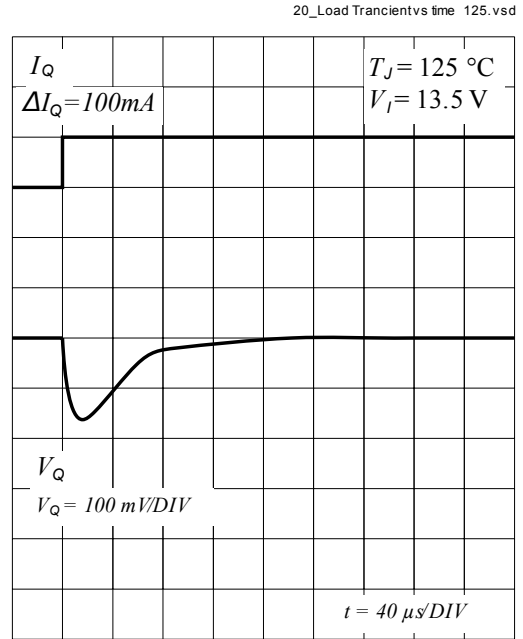


Typical Performance Characteristics

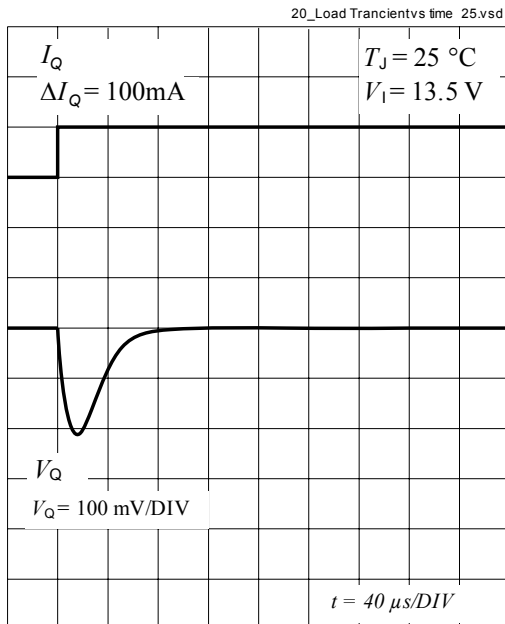
Line Regulation ΔV_Q versus Input Voltage Change V_I



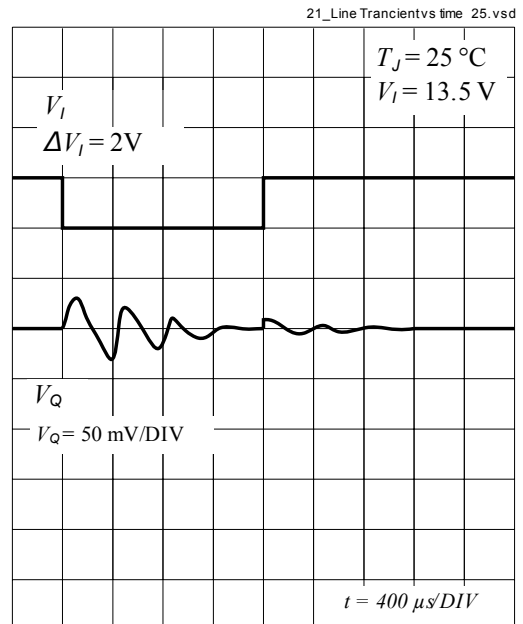
Load Transient Response Peak Voltage ΔV_Q



Load Transient Response Peak Voltage ΔV_Q

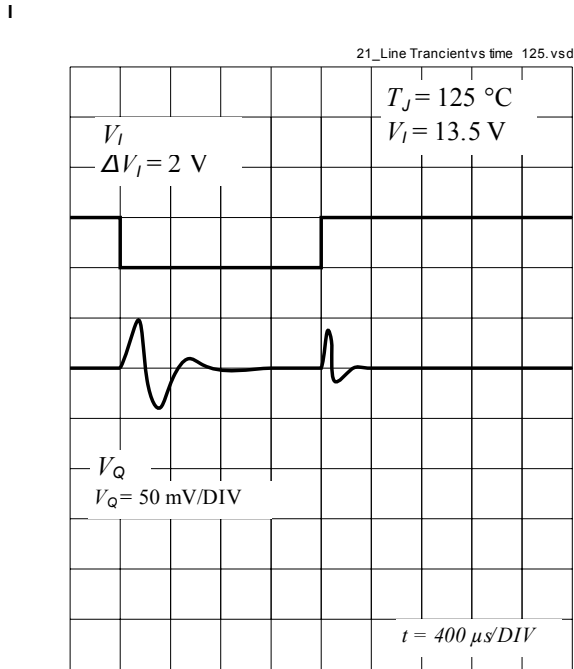


Line Transient Response Peak Voltage ΔV_Q

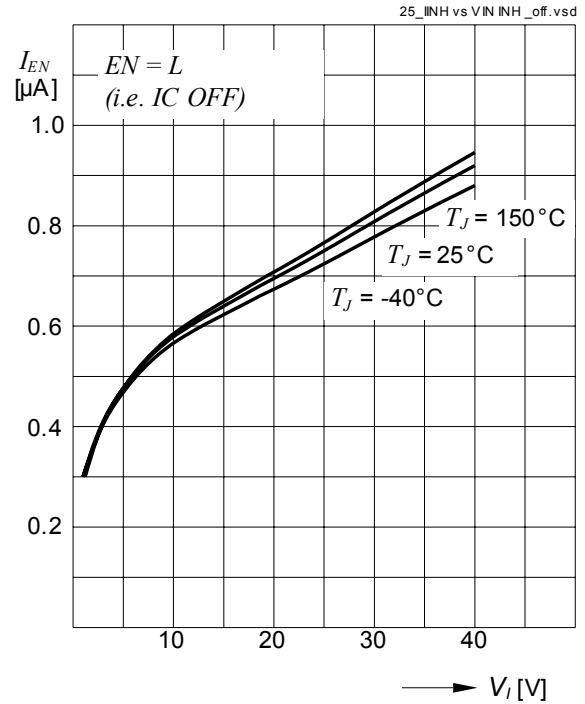


Typical Performance Characteristics

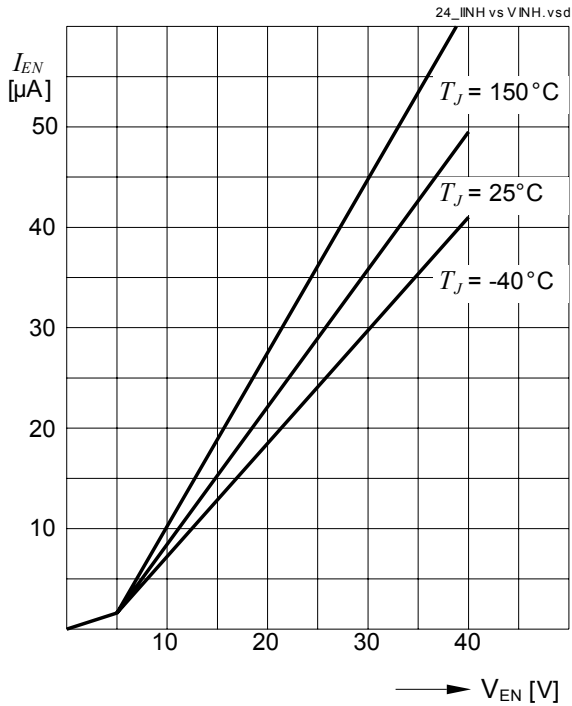
Line Transient Response Peak Voltage ΔV_Q



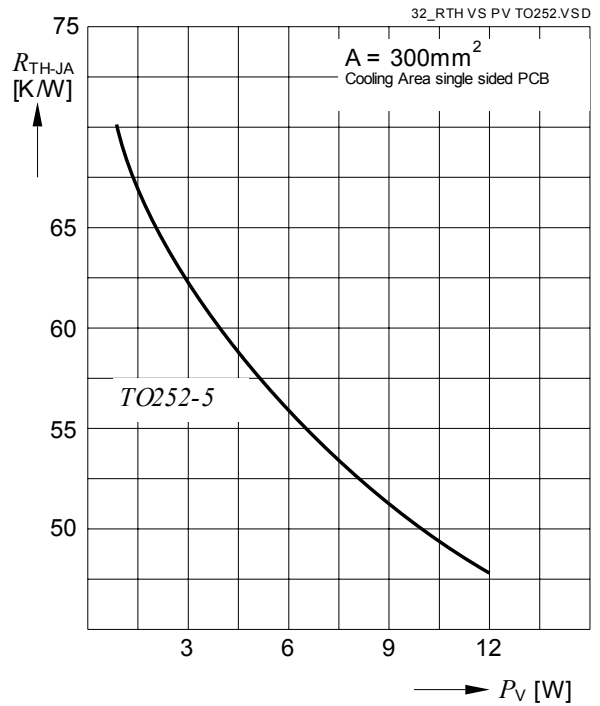
Enabled Input Current I_{EN} versus Input Voltage V_I , EN=Off



Enabled Input Current I_{EN} versus Enabled Input Voltage V_{EN}



Thermal Resistance Junction-Ambient R_{THJA} versus Power Dissipation P_V



6 Application Information

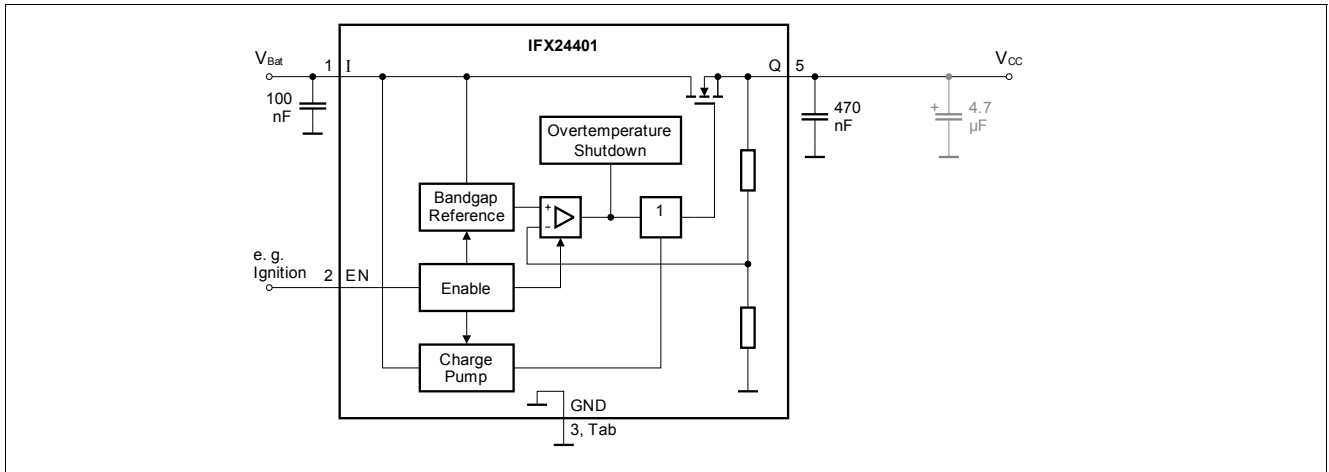


Figure 4 Application Diagram

Input, Output

An input capacitor is necessary for damping line influences. A resistor of approx. 1 Ω in series with C_I, can damp the LC of the input inductivity and the input capacitor.

The IFX24401 requires a ceramic output capacitor of at least 470 nF. In order to damp influences resulting from load current surges it is recommended to add an additional electrolytic capacitor of 4.7 μF to 47 μF at the output as shown in [Figure 4](#).

Additionally a buffer capacitor C_B of > 10μF should be used for the output to suppress influences from load surges to the voltage levels. This one can either be an aluminum electrolytic capacitor or a tantalum capacitor following the application requirements.

A general recommendation is to keep the drop over the equivalent serial resistor (ESR) together with the discharge of the blocking capacitor below the allowed Headroom of the Application to be supplied (e.g. typ. dV_Q = 350mV).

Since the regulator output current roughly rises linearly with time the discharge of the capacitor can be calculated as follows:

$$dV_{C_B} = dI_Q \cdot dt / C_B$$

The drop across the ESR calculates as:

$$dV_{ESR} = dI \cdot ESR$$

To prevent a reset the following relationship must be fulfilled:

$$dV_C + dV_{ESR} < V_{RH} = 350mV$$

Example: Assuming a load current change of dI_Q = 100mA, a blocking capacitor of C_B = 22μF and a typical regulator reaction time under normal operating conditions of dt ~ 25μs and for special dynamic load conditions, such as load step from very low base load, a reaction time of dt ~ 75μs.

$$dV_C = dI_Q \cdot dt / C_B = 100mA \cdot 25\mu s / 22\mu F = 113mV$$

So for the ESR we can allow

$$dV_{ESR} = V_{RH2} - dV_C = 350mV - 113mV = 236mV$$

The permissible ESR becomes:

$$ESR = dV_{ESR} / dI_Q = 236mV / 100mA = 2.36\Omega$$

7 Package Outlines

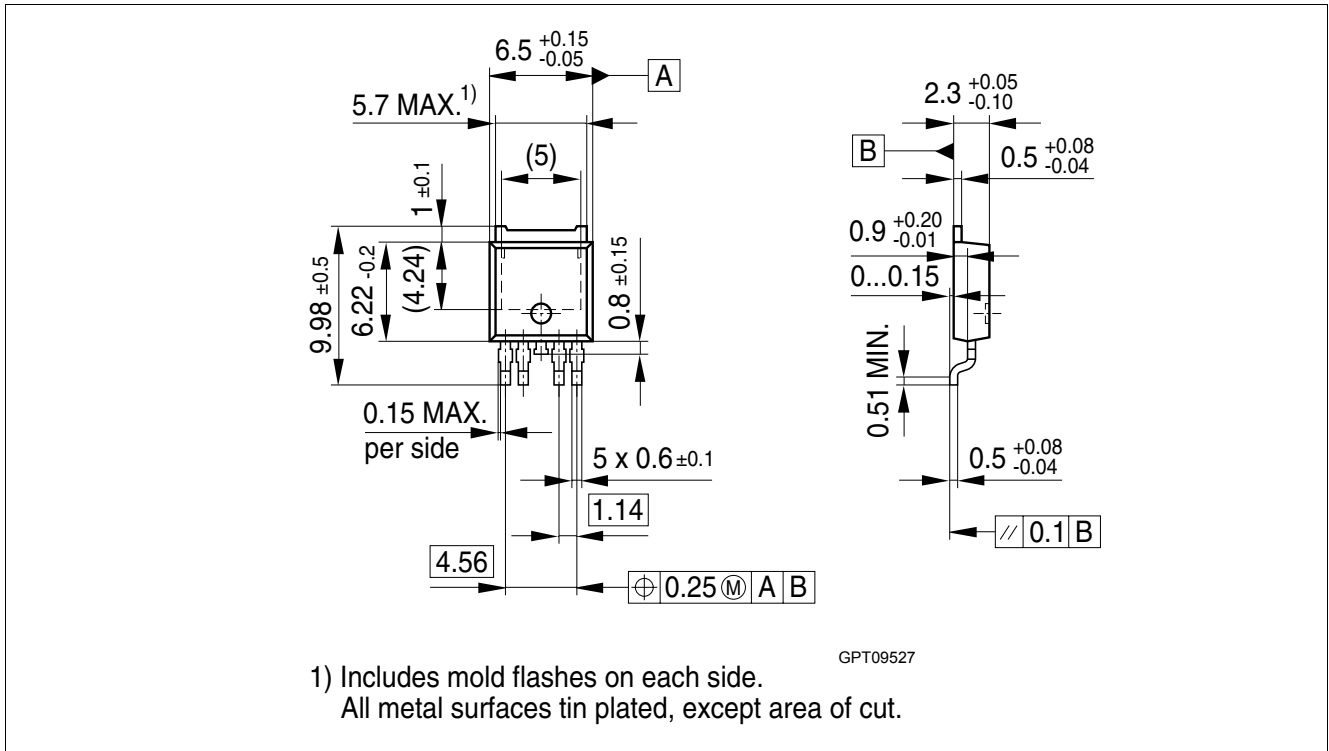


Figure 5 PG-TO252-5

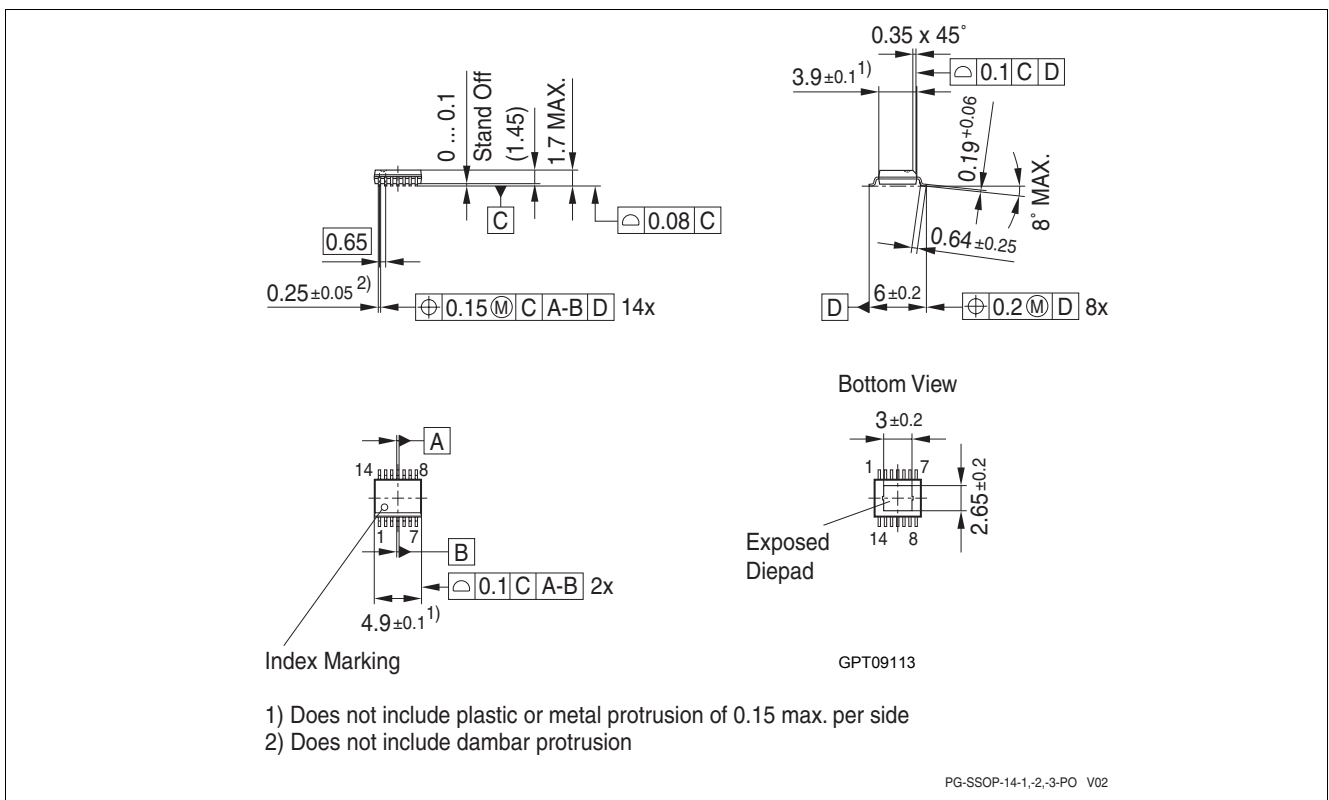


Figure 6 PG-SSOP-14

8 Revision History

| Revision | Date | Changes |
|----------|------------|---|
| 1.02 | 2009-12-10 | Corrections to pin assignment |
| 1.01 | 2009-10-19 | Coverpage changed Overview page: Inserted reference statement to TLE/TLF series. |
| 1.0 | 2009-04-28 | Initial Release |

Edition 2009-12-10

**Published by
Infineon Technologies AG
81726 Munich, Germany**

**© 2009 Infineon Technologies AG
All Rights Reserved.**

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Infineon:](#)

[IFX24401EL V50](#) [IFX24401TE V50](#)